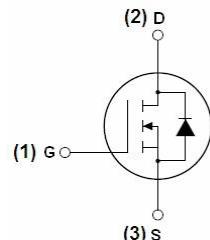


# 3N10

# 100V N-Channel Enhancement Mode MOSFET

## Description

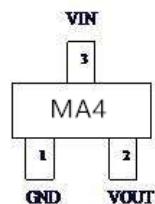
The 3N10 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.



## General Features

$V_{DS} = 100V$   $I_D = 2.8A$

$R_{DS(ON)} < 310m\Omega$  @  $V_{GS}=10V$



## Application

Battery protection

Load switch

Uninterruptible power supply

## Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
3N10	SOT23	MA4	3000

## Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ C$ )	2.8	A
	Drain Current – Continuous ( $T_c=100^\circ C$ )	1.5	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	6.8	A
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	1.76	W
	Power Dissipation – Derate above $25^\circ C$	0.014	W/ $^\circ C$
$T_{STG}$	Storage Temperature Range	-50 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-50 to 150	$^\circ C$

**100V N-Channel Enhancement Mode MOSFET**
**Thermal Characteristics**

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	70	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	30	°C/W

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

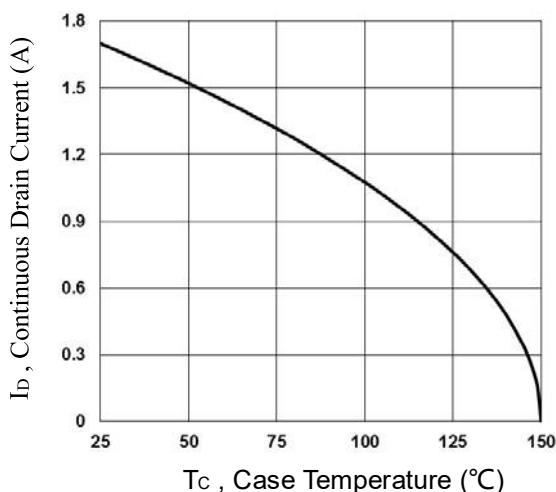
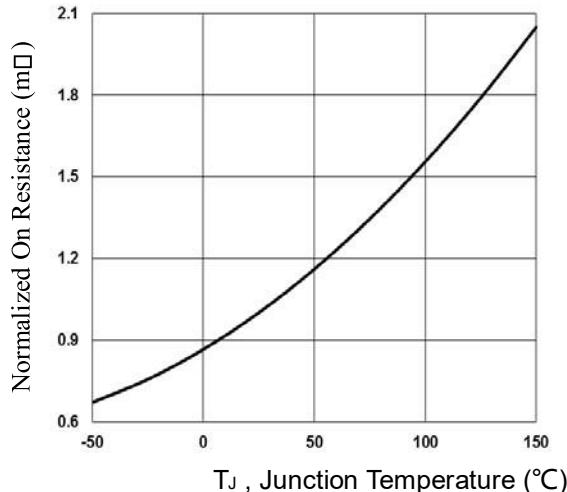
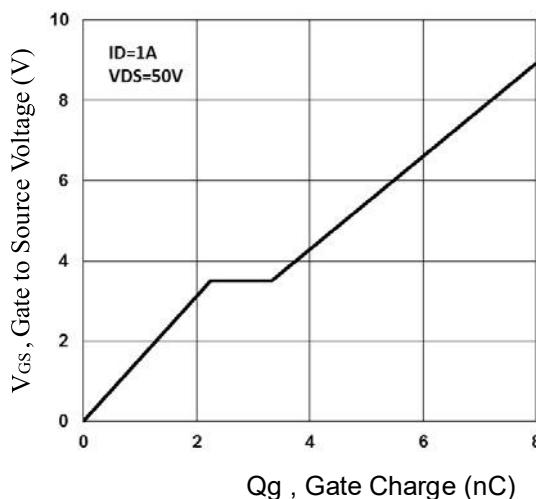
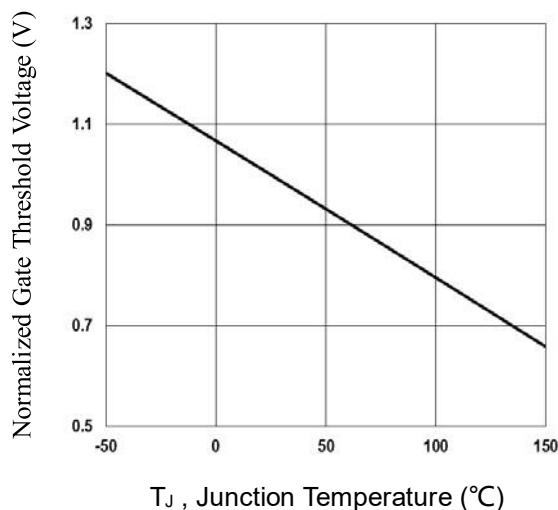
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	100	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA	---	0.09	---	V/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =100V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =80V , V <sub>GS</sub> =0V , T <sub>J</sub> =125°C	---	---	10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V	---	---	±100	nA
R <sub>Ds(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V , I <sub>D</sub> =1A	---	260	310	mΩ
		V <sub>GS</sub> =4.5V , I <sub>D</sub> =0.5A	---	270	320	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.2	1.8	2.5	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	-5	---	mV/°C
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =10V , I <sub>D</sub> =2A	---	2.3	---	S
Q <sub>g</sub>	Total Gate Charge <sup>2,3</sup>	V <sub>DS</sub> =50V , V <sub>GS</sub> =10V , I <sub>D</sub> =1A	---	9	18	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>2,3</sup>		---	2.3	4.6	
Q <sub>gd</sub>	Gate-Drain Charge <sup>2,3</sup>		---	1.1	2.5	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>2,3</sup>	V <sub>DD</sub> =50V , V <sub>GS</sub> =10V , R <sub>G</sub> =3.3 I <sub>D</sub> =1A	---	5.2	10	ns
T <sub>r</sub>	Rise Time <sup>2,3</sup>		---	6.8	12	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>2,3</sup>		---	14.5	28	
T <sub>f</sub>	Fall Time <sup>2,3</sup>		---	2.1	5	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V , V <sub>GS</sub> =0V , F=1MHz	---	492	800	pF
C <sub>oss</sub>	Output Capacitance		---	27	50	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	15	25	
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz	---	2.8	5.6	

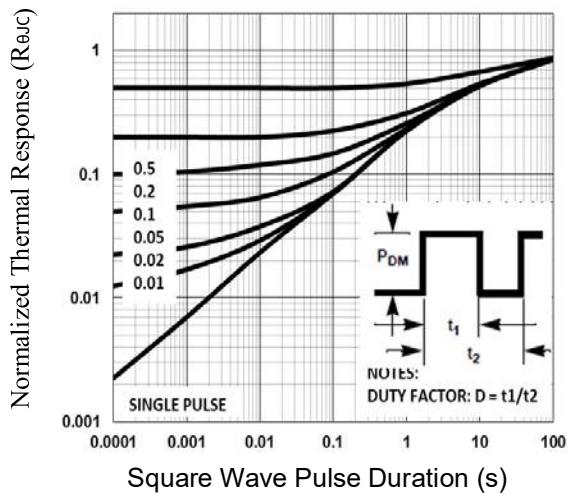
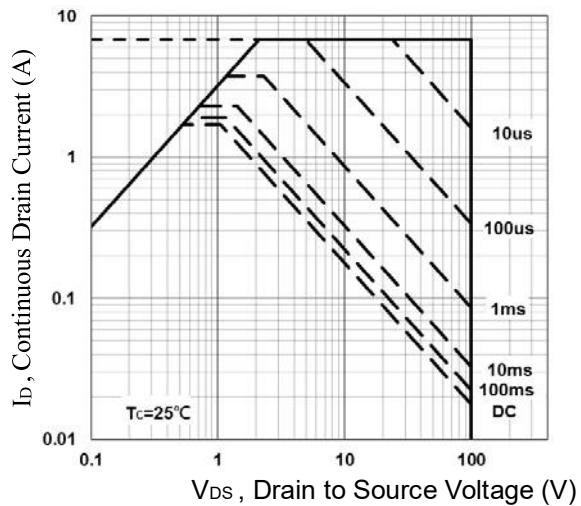
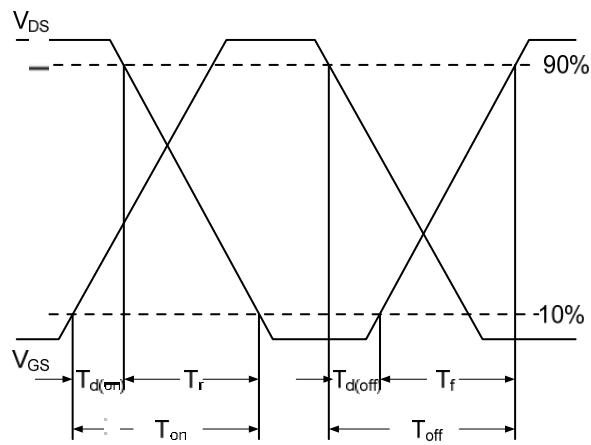
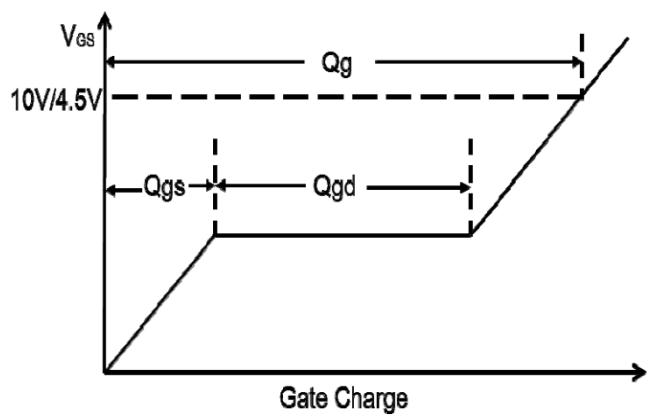
**100V N-Channel Enhancement Mode MOSFET**
**Drain-Source Diode Characteristics and Maximum Ratings**

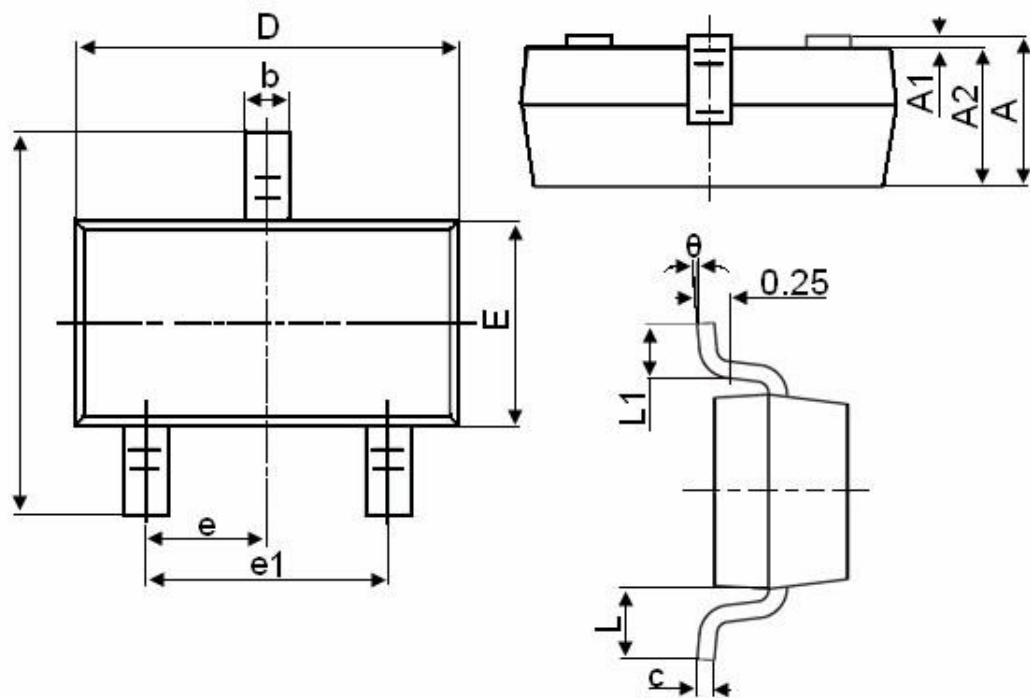
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>s</sub>	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	4	A
			---	---	8	A
I <sub>SM</sub>	Pulsed Source Current		---	---	1	V
V <sub>SD</sub>	Diode Forward Voltage	$V_{GS}=0V$ , $I_S=1A$ , $T_J=25^\circ C$	---	---	1	V
t <sub>rr</sub>	Reverse Recovery Time <sup>2</sup>	$I_S=1A$ , $dI/dt=100A/\mu s$	---	---	---	ns
Q <sub>rr</sub>	Reverse Recovery Charge <sup>2</sup>	$T_J=25^\circ C$	---	---	---	nC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
23. Essentially independent of operating temperature. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .


**Fig.1 Continuous Drain Current vs.  $T_c$** 

**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$** 


**100V N-Channel Enhancement Mode MOSFET**
**Fig.3 Normalized  $V_{th}$  vs.  $T_J$** 

**Fig.4 Gate Charge Waveform**

**Fig.5 Normalized Transient Impedance**

**Fig.6 Maximum Safe Operation Area**

**Fig.7 Switching Time Waveform**

**100V N-Channel Enhancement Mode MOSFET**
**SOT-23 Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.520	1.800	0.060	0.071
A1	0.000	0.100	0.000	0.004
A2	1.500	1.700	0.059	0.067
b	0.660	0.820	0.026	0.032
c	0.250	0.350	0.010	0.014
D	6.200	6.400	0.244	0.252
D1	2.900	3.100	0.114	0.122
E	3.300	3.700	0.130	0.146
E1	6.830	7.070	0.269	0.278
e	2.300 (BSC)		0.091 (BSC)	
e1	4.500	4.700	0.177	0.185
L	0.900	1.150	0.035	0.045
$\theta$	0°	10°	0°	10°